



CSP-59 Lead Free RoHS Profile

Total Mass of the Unit specified (g)	Product / Component Description	Breakdown of product / component (e.g. chassis, transformer, lead frame, encapsulation, etc.)	Material Name (e.g. Sn alloy)	Substance Name (e.g. Copper (Cu))	CAS No.	Substance Mass (mg)	PPM	Additional Information
0.042	59 Ball CSP	IC Chip	Silicon doped with aluminium	Silicon (Si)	7440-21-3	30.45423	717,912	
		IC Chip	Silicon doped with aluminium	Aluminium (Al)	7429-90-5	0.01820	429	
		Metalization	UBM	Aluminium (Al)	7429-90-5	0.01130	266	
		Metalization	UBM	Nickel (Ni)	7440-02-0	0.00565	133	
		Metalization	UBM	Vanadium (V)	7440-62-2	0.00565	133	
		Metalization	UBM	Copper (Cu)	7440-50-8	0.04502	1,061	
		Metalization	BCB			0.06839	1,612	Cyclotene 4022-35
		IC Solderball	Solderball	Tin (Sn)	7440-31-5	11.28071	265,926	
		IC Solderball	Solderball	Silver (Ag)	7440-22-4	0.47243	11,137	
		IC Solderball	Solderball	Copper (Cu)	7440-50-8	0.059	1,391	

Total mass (mg)	42.421
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